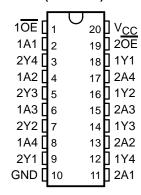
SN54LVT244B, SN74LVT244B 3.3-V ABT OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

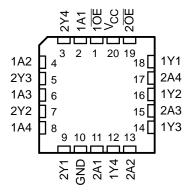
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- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low-Static Power Dissipation
- High-Impedance State During Power Up and Power Down
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Power Off Disables Inputs/Outputs, Permitting Live Insertion
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Packages, and Ceramic (J) DIPs

SN54LVT244B . . . J OR W PACKAGE SN74LVT244B . . . DB, DW, OR PW PACKAGE (TOP VIEW)



SN54LVT244B . . . FK PACKAGE (TOP VIEW)



description

These octal buffers and line drivers are designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

The 'LVT244B is organized as two 4-bit line drivers with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the device passes data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state.

When V_{CC} is between 0 and 1.5 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74LVT244B is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed circuit board area.

The SN54LVT244B is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74LVT244B is characterized for operation from –40°C to 85°C.



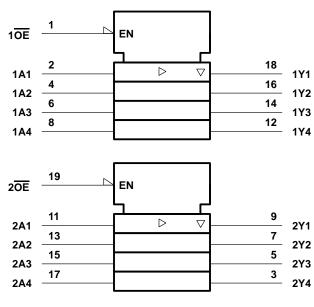
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FUNCTION TABLE (each buffer)

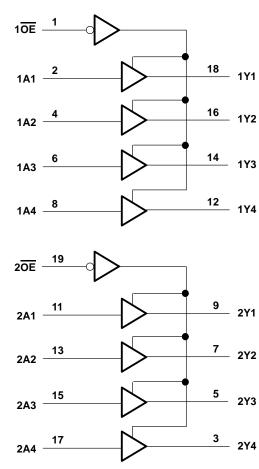
INP	JTS	OUTPUT
OE	Α	Y
L	Н	Н
L	L	L
н	Χ	Z

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



SCAS354C - FEBRUARY 1994 - REVISED NOVEMBER 1996

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, VO (see Note 1)	0.5 V to 7 V
Current into any output in the low state, IO: SN54LVT244B	96 mA
SN74LVT244B	128 mA
Current into any output in the high state, IO (see Note 2): SN54LVT244B	48 mA
SN74LVT244B	64 mA
Input clamp current, I _{IK} (V _I < 0)	–50 mA
Output clamp current, I_{OK} ($V_O < 0$)	
Maximum power dissipation at $T_A = 55^{\circ}$ C (in still air) (see Note 3): DB package	
DW package	1.6 W
PW package	0.7 W
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. This current flows only when the output is in the high state and $V_O > V_{CC}$.

3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the *ABT Advanced BiCMOS Technology Data Book*.

recommended operating conditions (see Note 4)

		SN54LV	Г244В	SN74LV	UNIT		
			MIN	MAX	MIN	MAX	UNII
VCC	Supply voltage	2.7	3.6	2.7	3.6	V	
V_{IH}	High-level input voltage				2		V
V _{IL}	Low-level input voltage					8.0	V
VI	Input voltage	4	5.5		5.5	V	
ЮН	High-level output current	7	-24		-32	mA	
loL	Low-level output current	20	48		64	mA	
Δt/Δν	Input transition rise or fall rate	Outputs enabled	00	10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T _A	Operating free-air temperature	– 55	125	-40	85	°C	

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.

SN54LVT244B, **SN74LVT244B** 3.3-V ABT OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCAS354C - FEBRUARY 1994 - REVISED NOVEMBER 1996

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER	TEST CONDITIONS				54LVT24	4B	SN74LVT244B			LINUT		
PARAMETER	· '	MIN	TYP†	MAX	MIN	TYP [†]	MAX	UNIT				
VIK	$V_{CC} = 2.7 \text{ V},$	I _I = -18 mA			-1.2			-1.2	V			
	$V_{CC} = MIN \text{ to } MAX^{\ddagger},$	$I_{OH} = -100 \mu A$	V _{CC} -0	.2		V _{CC} -0	.2					
V	$V_{CC} = 2.7 \text{ V},$	$I_{OH} = -8 \text{ mA}$		2.4			2.4			V		
VOH	VCC = 3 V	$I_{OH} = -24 \text{ mA}$	2						V			
	∧CC = 2 ∧	$I_{OH} = -32 \text{ mA}$				2						
	V _{CC} = 2.7 V	I _{OL} = 100 μA				0.2			0.2			
	VCC = 2.7 V	I _{OL} = 24 mA				0.5			0.5			
V		I _{OL} = 16 mA			0.4		٧					
V_{OL}	\\\\-\ \-\ \\\\\\\\\\\\\\\\\\\\\\\\\\\	I _{OL} = 32 mA			0.5	0.5						
	V _{CC} = 3 V	I _{OL} = 48 mA			0.55							
		I _{OL} = 64 mA			E			0.55				
	$V_{CC} = 0$ or MAX ‡ ,	V _I = 5.5 V		2	10			10				
1.	V _{CC} = 3.6 V	$V_I = V_{CC}$ or GND	Control inputs ±1						±1	±1 μA		
tį		VI = VCC	Data innuta	1 -5			1 -5			μΑ		
		V _I = 0	Data inputs									
l _{off}	$V_{CC} = 0$,	$V_{1} \text{ or } V_{O} = 0 \text{ to } 4.5 \text{ V}_{O}$	/	20),				±100	μΑ		
I _{OZPU} §	$V_{CC} = 0 \text{ to } 1.5 \text{ V},$	$V_0 = 0.5 \text{ V to 3 V},$	OE = 0			±100			±100	μΑ		
I _{OZPD} §	$V_{CC} = 1.5 \text{ V to } 0,$	$V_0 = 0.5 \text{ V to 3 V},$	OE = 0			±100			±100	μΑ		
lozh	$V_{CC} = 3.6 \text{ V},$	V _O = 3 V				5			5	μΑ		
lozL	$V_{CC} = 3.6 \text{ V},$	$V_0 = 0.5 V$				- 5			– 5	μΑ		
			Outputs high			0.19			0.19			
100	$V_{CC} = 3.6 \text{ V},$	$I_O = 0$,	Outputs low			5			5	mA		
	V _I = V _{CC} or GND		Outputs disabled	0.19			0.19			1117 .		
ΔI _{CC} ¶	V_{CC} = 3 V to 3.6 V, One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND					0.3			0.2	mA		
Ci	V _I = 3 V or 0				4			4		pF		
Co	V _O = 3 V or 0				7			7		pF		

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$. ‡ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[§] This parameter is specified by characterization but is not tested.

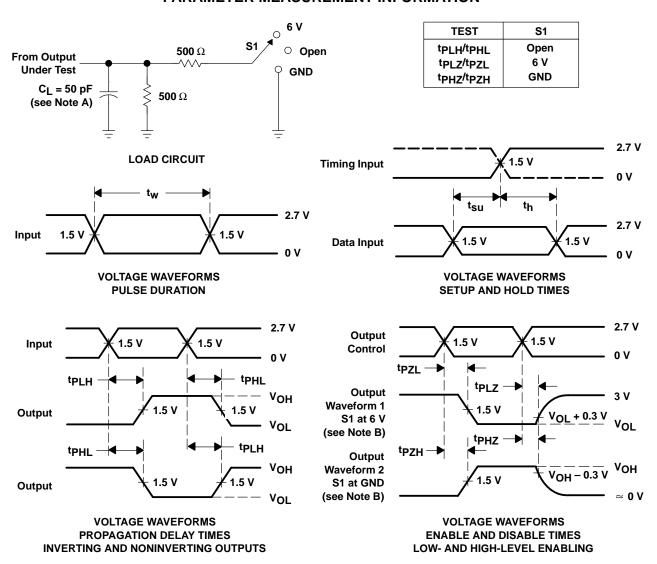
[¶] This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

		TO (OUTPUT)	SN54LVT244B			SN74LVT244B								
PARAMETER	FROM (INPUT)		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V			V _{CC} = 2.7 V		UNIT		
			MIN	MAX	MIN	MAX	MIN	TYP [†]	MAX	MIN	MAX			
^t PLH	Α	V	1	3.6	3/1/	3.9	1.1	2.3	3.5		3.8	ns		
^t PHL		ı	1.2	3.4	YY.	3.6	1.3	2.1	3.3		3.6	115		
^t PZH	ŌĒ	~	1	4.6/	1,	5.5	1.1	2.5	4.5		5.3	ns		
t _{PZL}		ı	1.3	4.5		5.1	1.4	2.7	4.4		4.9	115		
^t PHZ	OF.	Œ	9	~	1.8	4.5		4.7	1.9	2.8	4.4		4.5	ns
t _{PLZ}	OL .	r	1.7	4.5		4.6	1.8	2.9	4.4		4.4	110		

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq 2.5 \text{ ns.}$
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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